

What Is Claimed Is:

1. A press-fit diode, in particular for rectifier applications, comprising
  - a ode chip (7),
  - a se contact (3) for pressing the diode (1) into a substrate, which forms a first terminal of the press-fit diode (1), and
  - a re contact (2) which forms a second terminal of the press-fit diode (1),wherein the wire contact (2) is provided at least partially with a silver layer (10).
2. The press-fit diode as recited in Claim 1, wherein a section (5) of the wire contact (2) used for attaching the diode chip (7) is not provided with the silver layer (10).
3. The press-fit diode as recited in Claim 1 or 2, wherein the base contact (3) is not provided with the silver layer (10).
4. The press-fit diode as recited in one of the preceding claims, wherein the wire contact (2) has a nickel layer (6) on which the silver layer (10) is applied.
5. A method for manufacturing a press-fit diode (1), comprising
  - a ode chip (7),
  - a se contact (3) for pressing the diode (1) into a substrate, which forms a first terminal of the press-fit diode (1), and
  - a re contact (2) which forms a second terminal of the press-fit diode (1),

wherein the wire contact (2), in the single state, is provided at least partially with a silver layer (10), and the silver-plated wire contact (2), the base contact (3), and the diode chip (7) are subsequently connected to one another.

6. The method as recited in Claim 5, wherein a section (5) of the wire contact (2) used for attaching the diode chip (7) is not provided with the silver layer (10).
7. The method as recited in one of preceding Claims 5 through 7, wherein the base contact (3) is not provided with the silver layer (10).
8. The method as recited in one of preceding Claims 5 through 7, wherein the wire contact (2) is made of copper which is provided with a nickel layer (6) and a silver layer (10).